

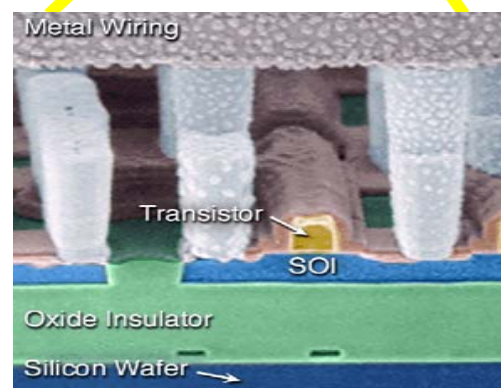
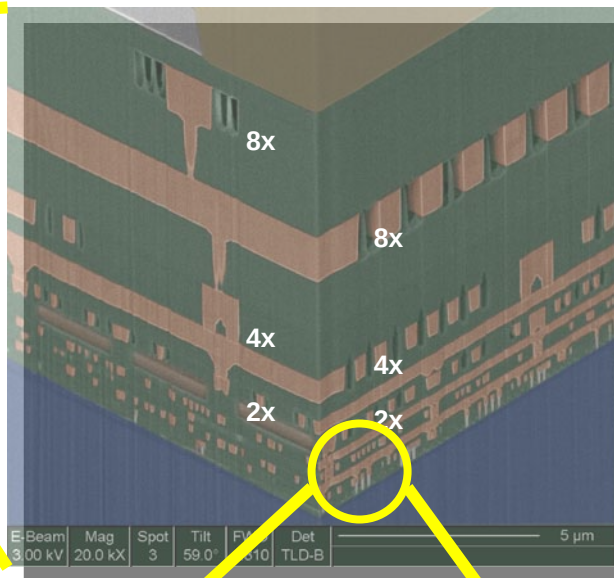
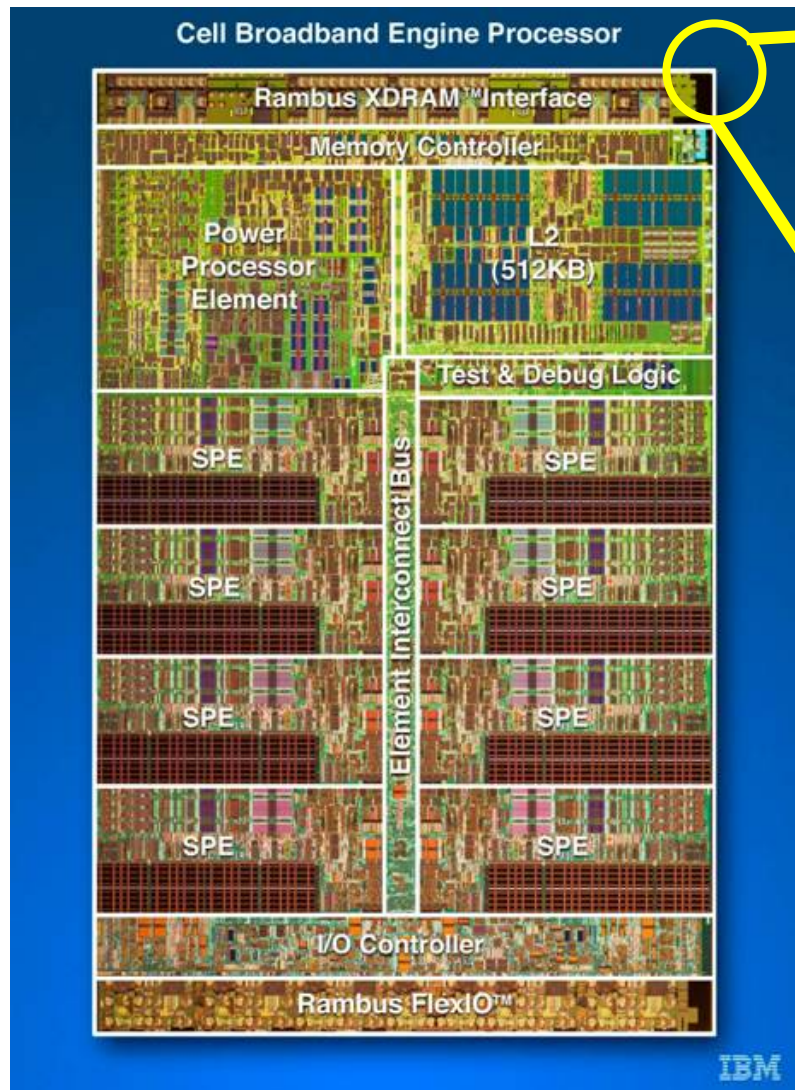
The Quest for the Next Information Processing Technology

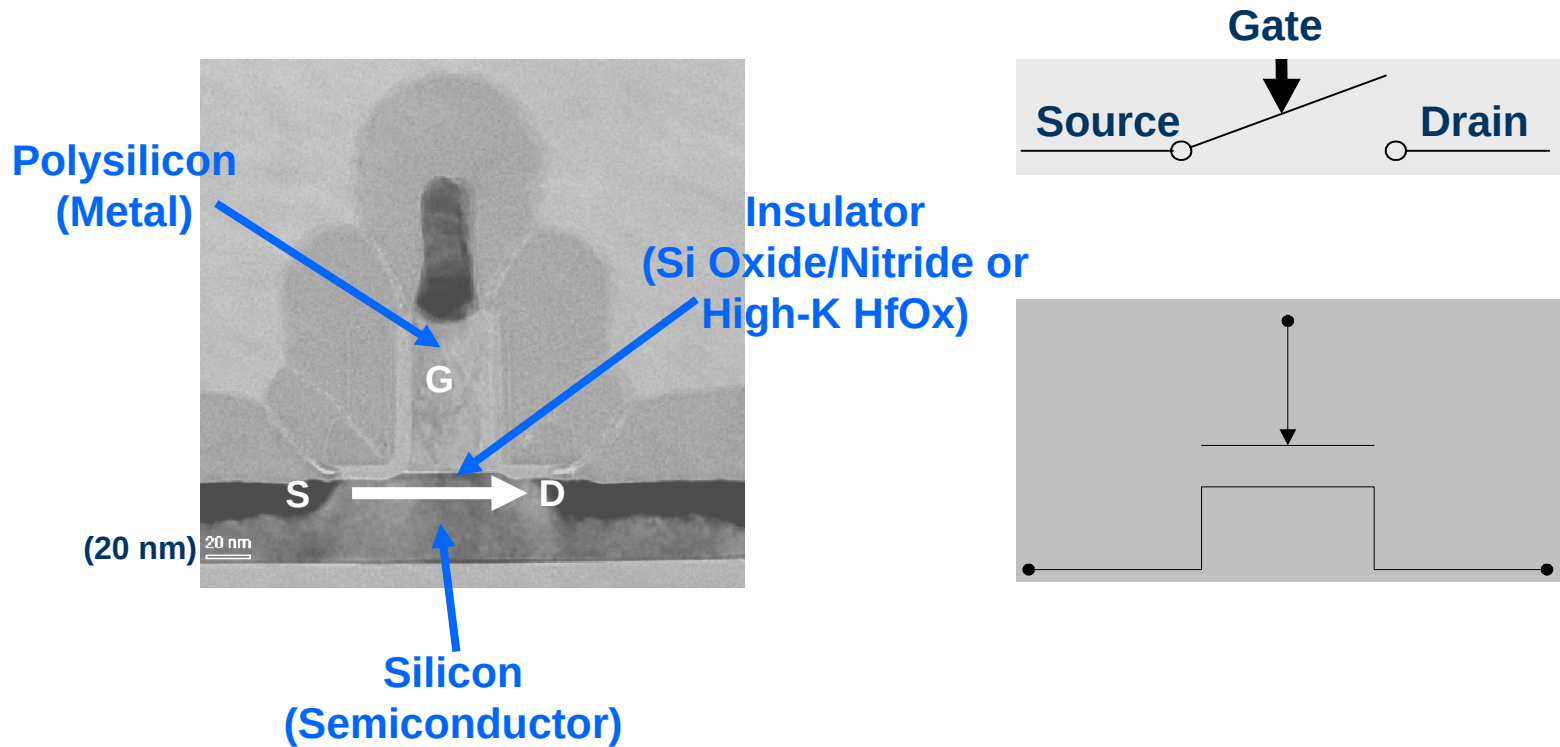
Dr. Jeff Welser

Director, SRC Nanoelectronics Research Initiative

IBM Almaden Research Center

September, 2008

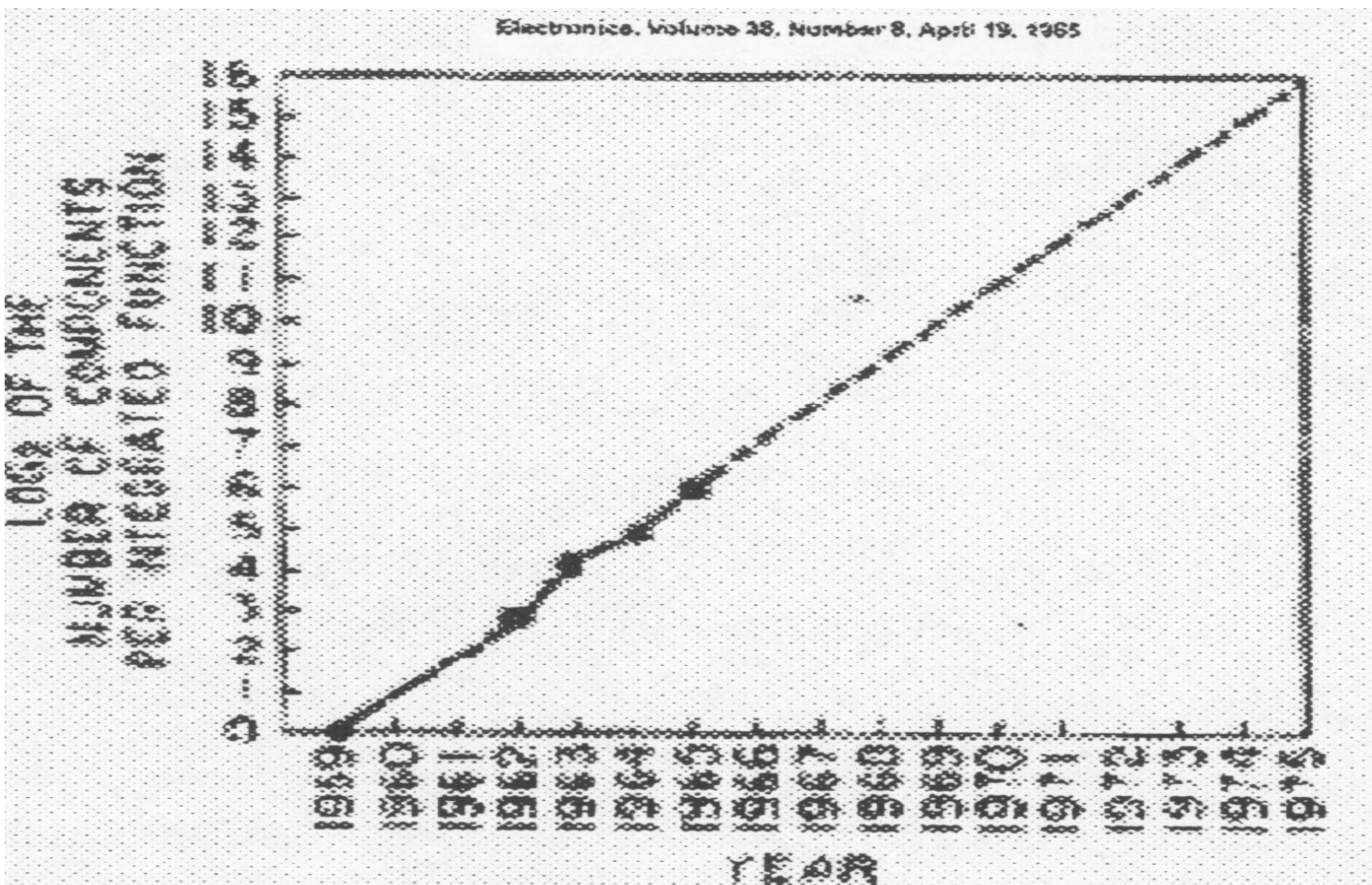




- Complementary Metal-Oxide-Semiconductor (CMOS) Field-Effect Transistor (FET)
 - N-type (electron carriers) and P-type (hole carriers) integrated together
 - Used primarily as a digital on/off switch
- Basic transistor used on digital Integrated Circuits (IC) chips
 - ~1 billion on the biggest chips today (~4 cm²)

Electronics, Volume 38, Number 8, April 19, 1965

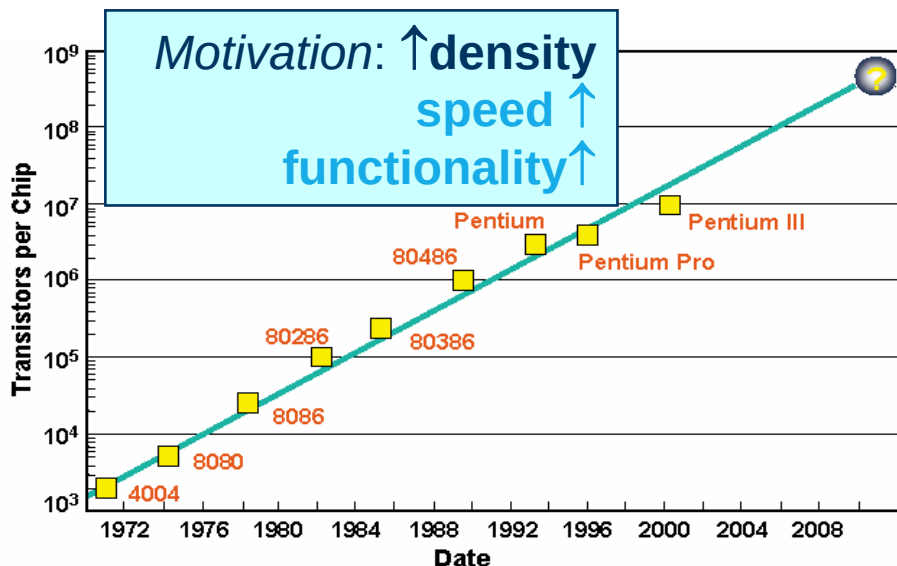
Log of the Number of Components
Per Integrated Function



Year

Moore's Law: Transistors per chip

Binary Information Throughput (BIT)



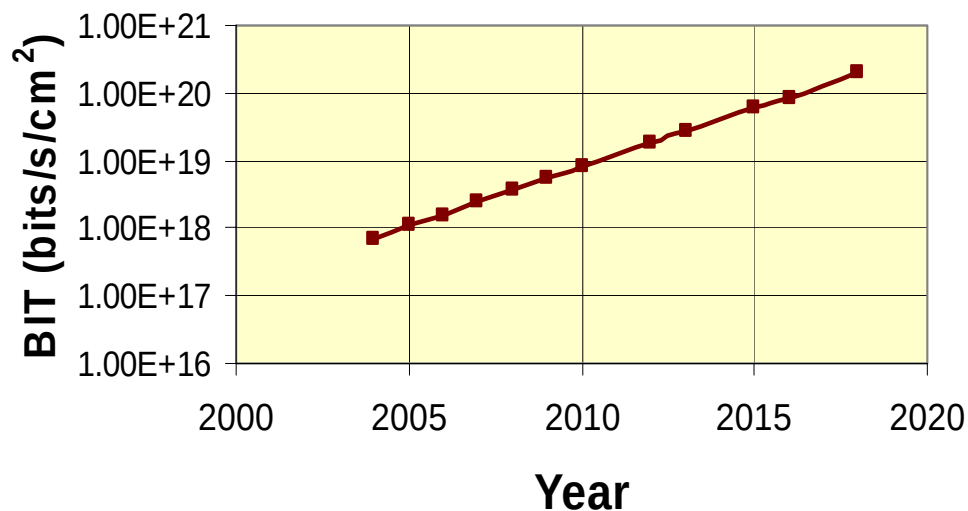
What is the ultimate number of binary transitions per second in a 1cm² chip area?

$$BIT = n_{bit} f$$

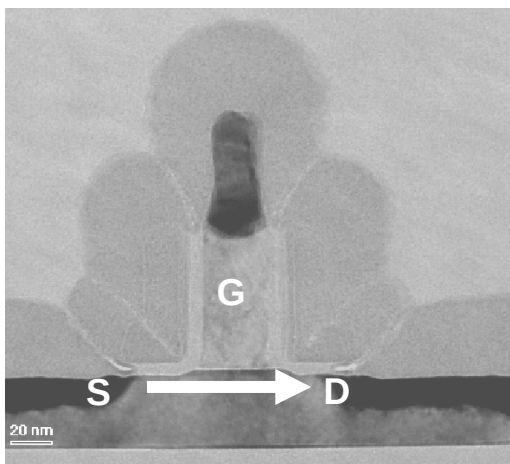
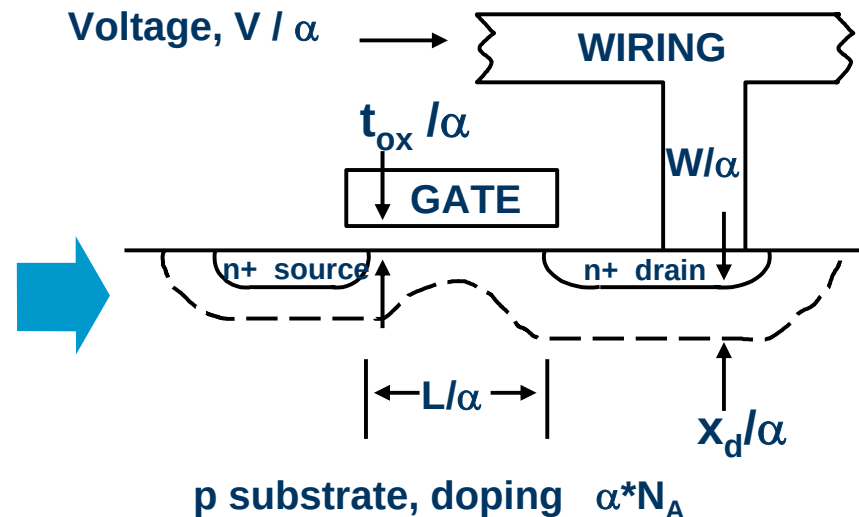
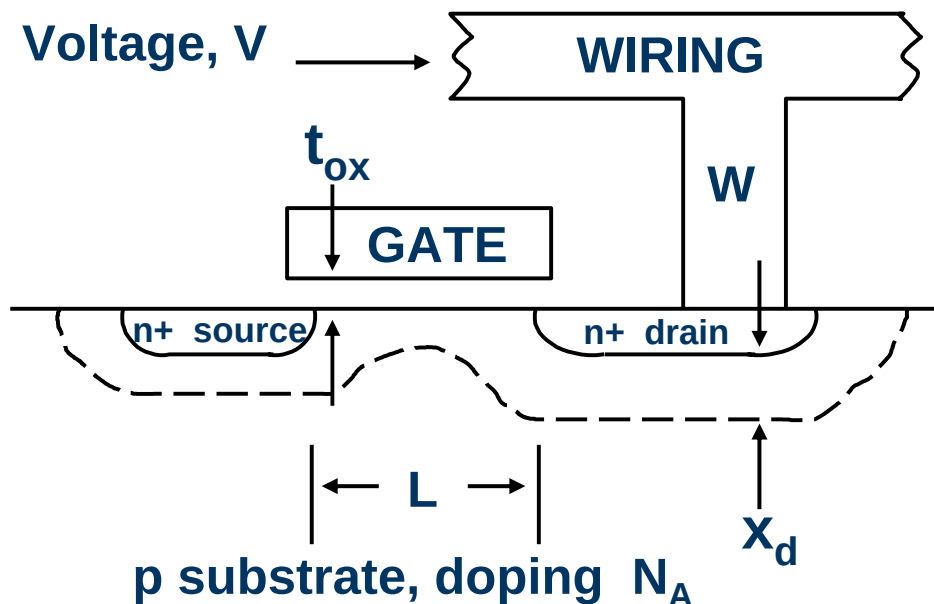
- a measure of computational capability on device level

n_{bit} – the number of binary states
 f – switching frequency

Why scaling? – To increase the *Binary Information Throughput* (BIT)



Source: Stan Williams, Hewlett Packard

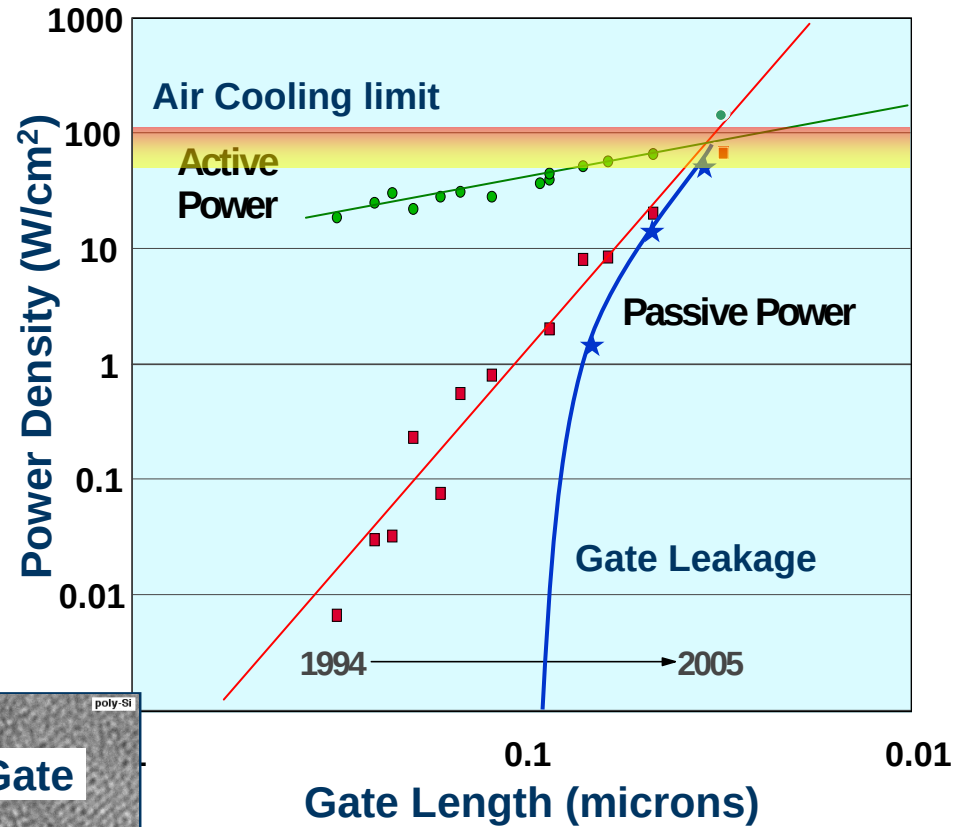
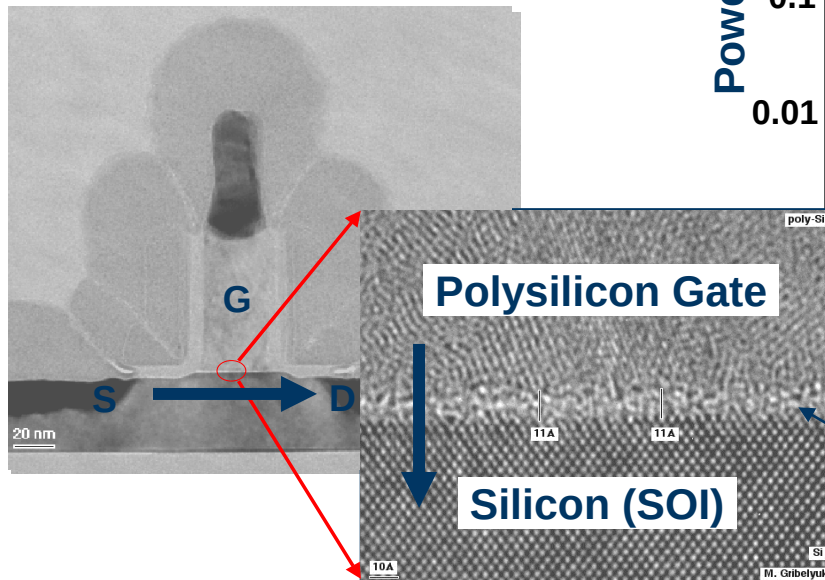


RESULTS:

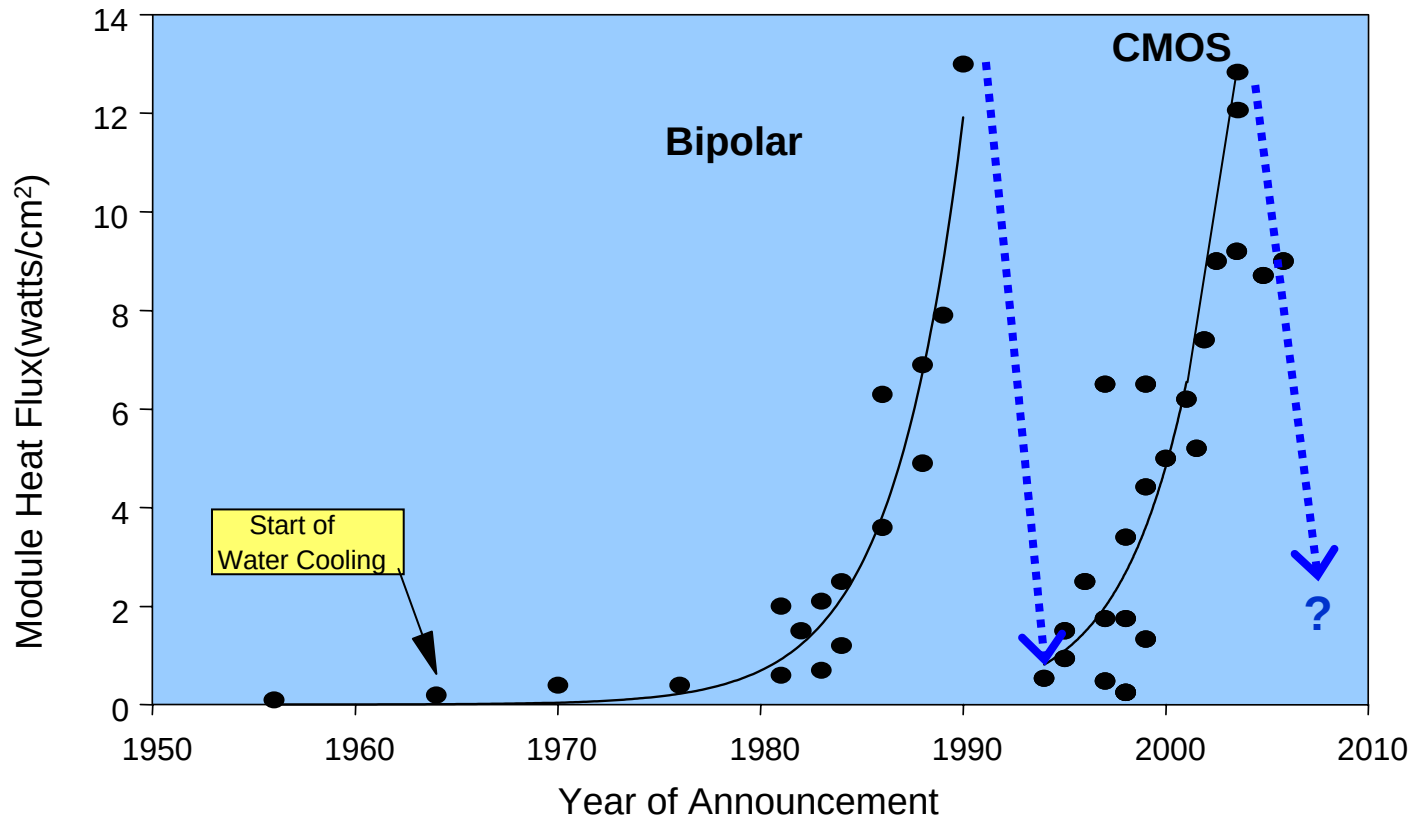
Higher Density:	α^2
Higher Speed:	α
Lower Power:	$1/\alpha^2$
per circuit	
Power Density:	Constant

■ Power components:

- Active power
- Passive power
 - Gate leakage
 - Source - Drain leakage



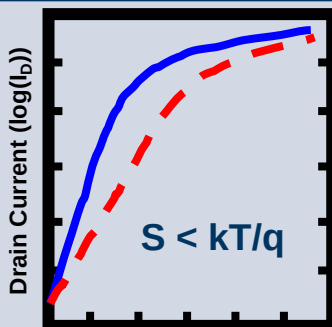
Has This Ever Happened Before?



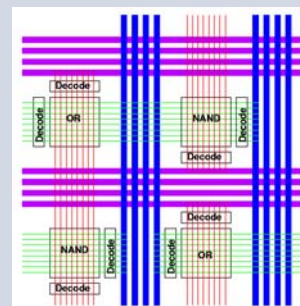
2005 ~ 2020: New utilization of technology

- Multi-core, 3D integration, new memory devices, sensors, etc.

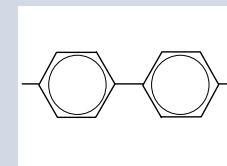
> 2020?: New technology → Nanoelectronics Research Initiative



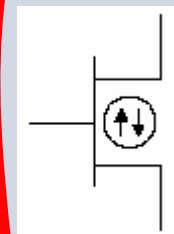
Gate Voltage (V_{GS})



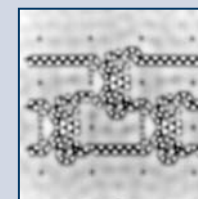
Fine-grain PLA



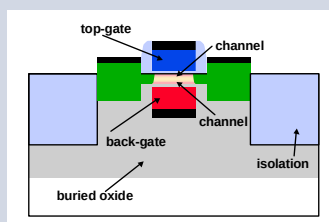
Molecular devices



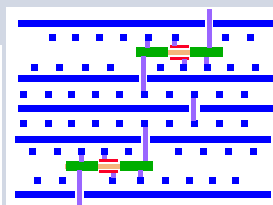
Spintronics



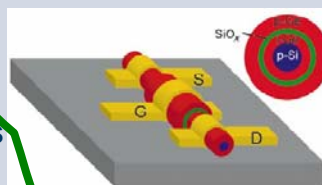
Quantum cascade



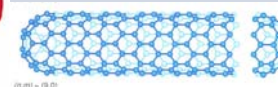
Double-Gate / FinFET



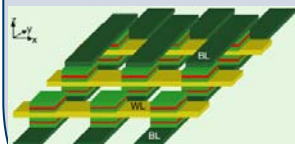
3D, heterogeneous integration



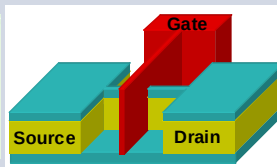
Nanowire



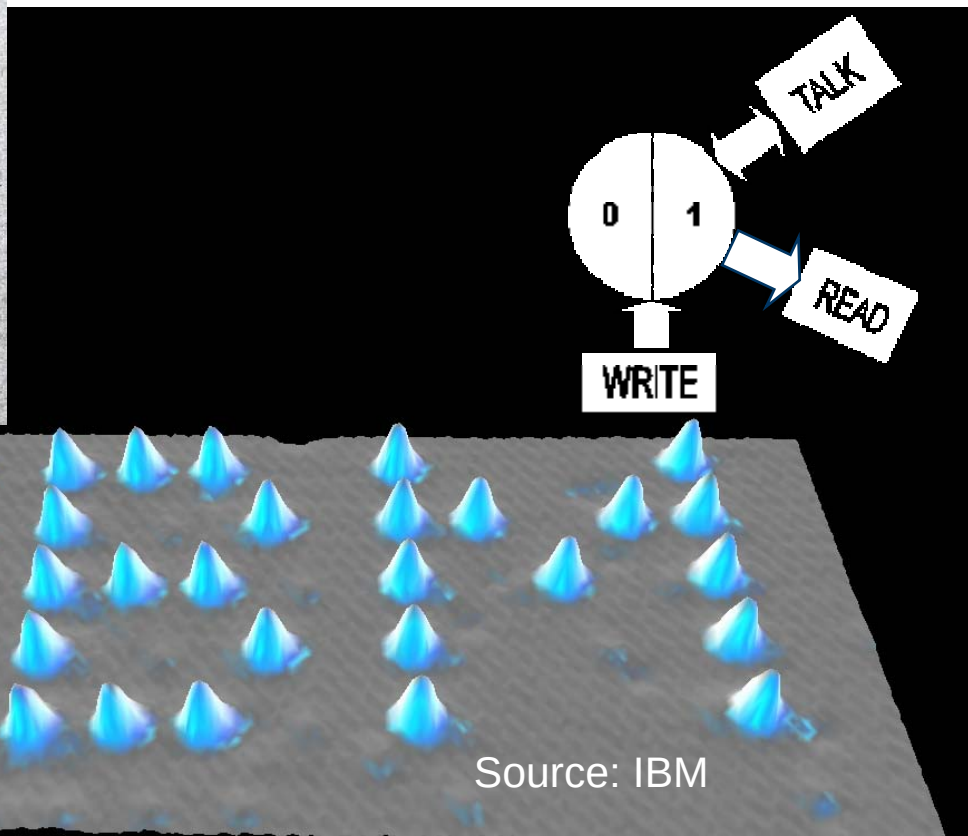
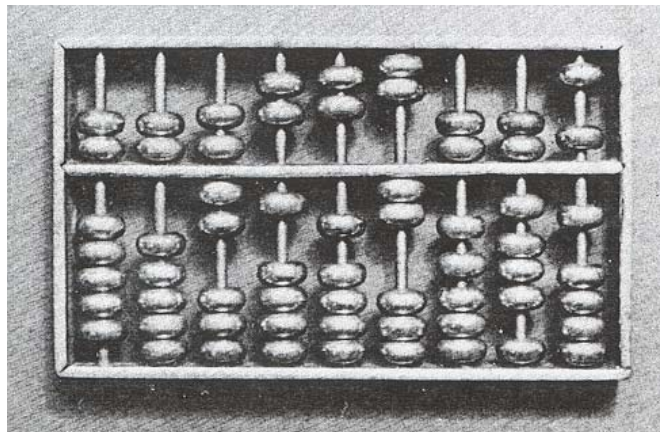
Nanotube



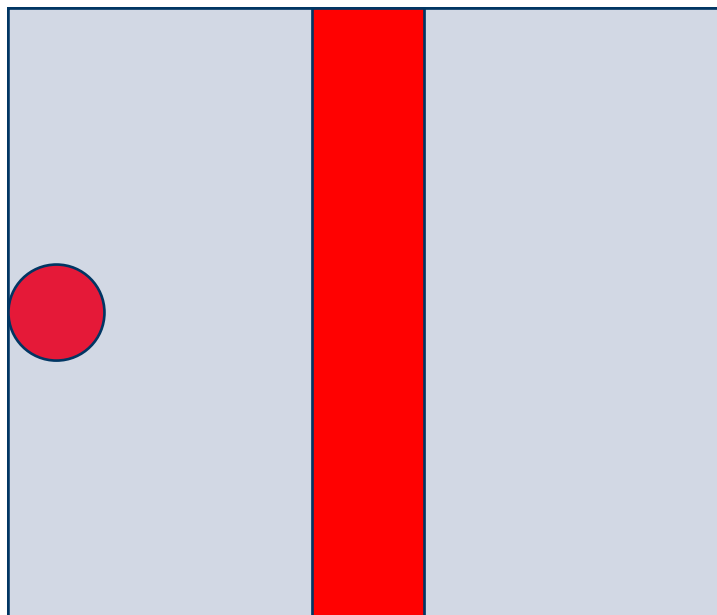
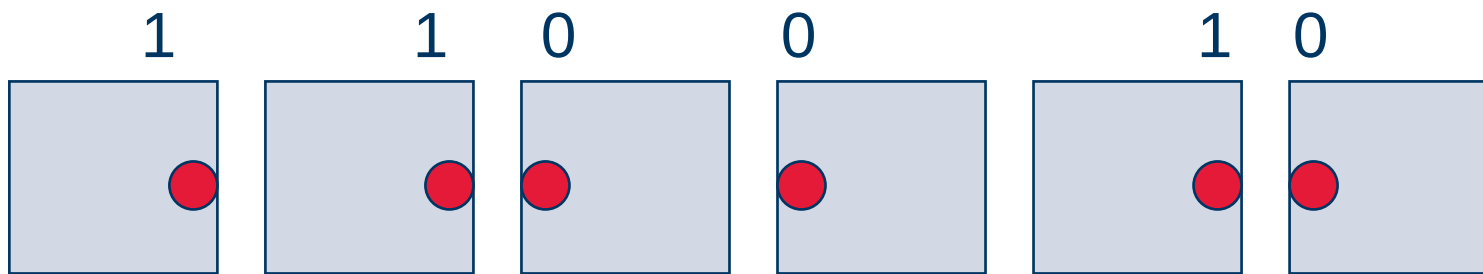
Embedded memory

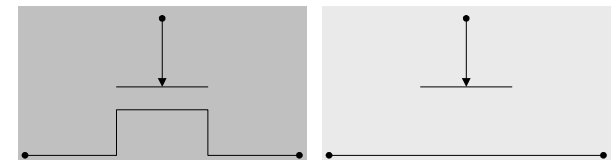
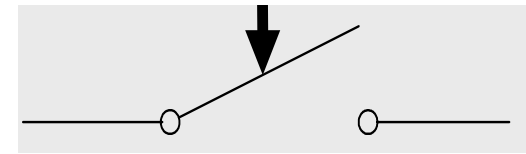
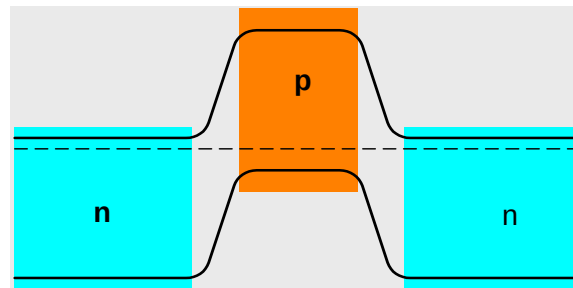
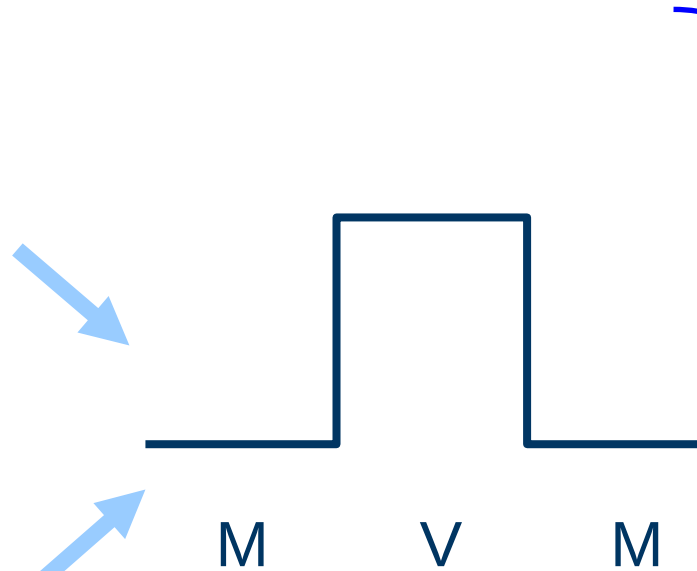
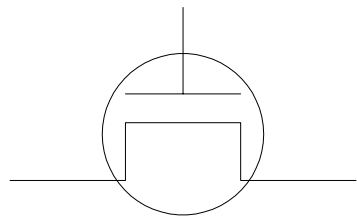
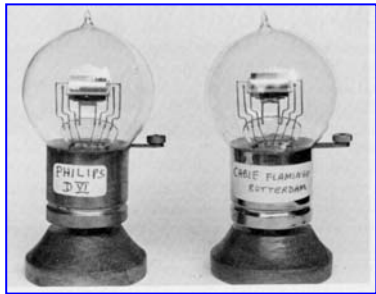
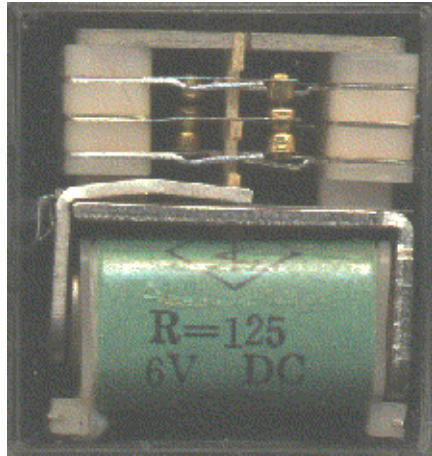


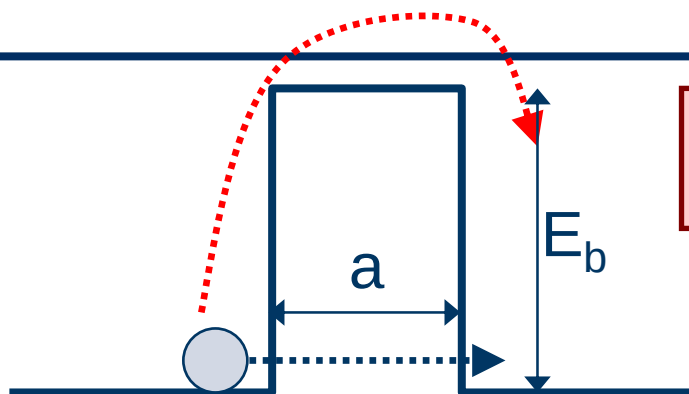
Time



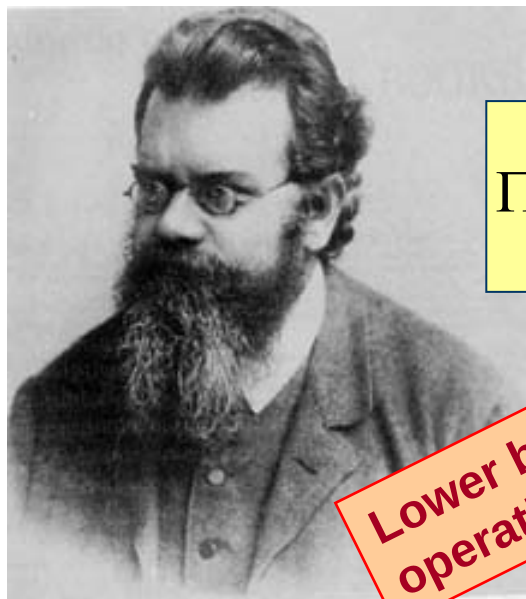
Information is measure of distinguishability
manifested in physical form







What are the requirements/limitations on the height and width the barrier?



$$\Pi_B = \exp\left(-\frac{E_b}{k_B T}\right)$$

Lower bound on operation energy

“Boltzmann constraint” on minimum barrier height



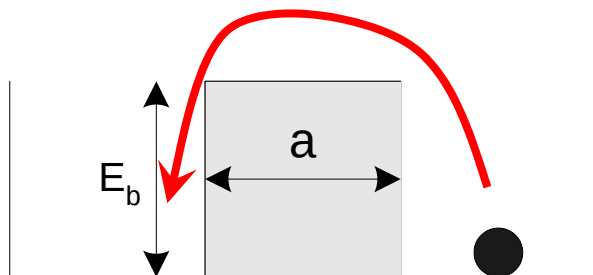
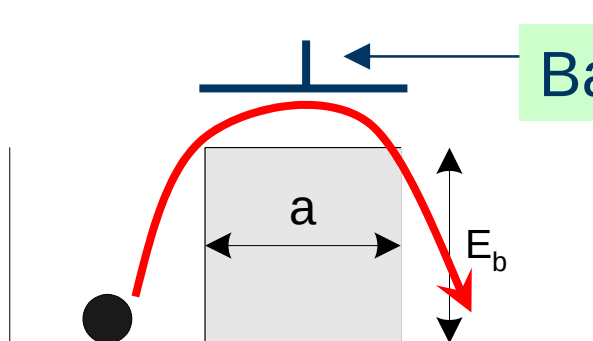
$$\Delta x \Delta p \geq \hbar/2$$

$$\Delta E \Delta t \geq \hbar/2$$

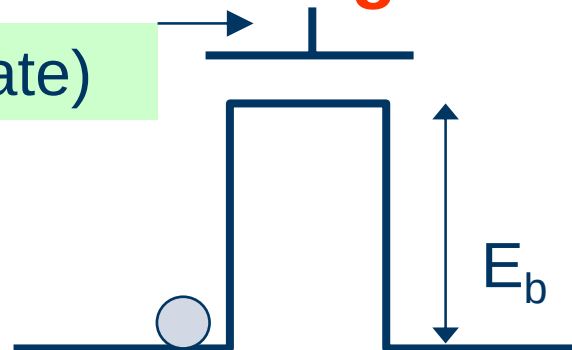
Lower bound on device size

“Heisenberg constraints” on minimum barrier width

How small could the energy barrier height be ?



OR



$$E_{bit}^{\min} = E_b$$

$$\Pi_{error} = \exp\left(-\frac{E_b}{k_B T}\right)$$

$$0.5 = \exp\left(-\frac{E_b}{k_B T}\right)$$

$$E_b^{\min} = k_B T \ln 2$$

Distinguishability requirement: The probability of spontaneous transitions(errors) $\Pi_{error} < 0.5$ (50%)



Energy to
"deform" the
barrier

1) Minimum energy per binary transition $\longrightarrow$

Boltzmann

$$E_{\text{bit}}^{\text{min}} = k_B T \ln 2$$

2) Minimum distance between two distinguishable states

$$\Delta x \Delta p \geq \hbar$$

$\longrightarrow$

Heisenberg

$$x_{\text{min}} = a = \frac{\hbar}{\sqrt{2mkT \ln 2}} = 1.5 \text{ nm}(300\text{K})$$

3) Minimum state switching time

$$\Delta E \Delta t \geq \hbar$$

$\longrightarrow$

Heisenberg

$$t_{\text{st}} = \frac{\hbar}{kT \ln 2} = 4 \times 10^{-14} \text{ s}(300\text{K})$$

4) Maximum gate density

$$n = \frac{1}{x_{\text{min}}^2} = 4.6 \times 10^{13} \frac{\text{gate}}{\text{cm}^2}$$



Total Power Dissipation (@ $E_{bit} = kT \ln(2)$)

- **A Catastrophe!**

$$P_{chip} = \frac{n \cdot E_{bit}}{t} = 4.6 \cdot 10^{13} [cm^{-2}] \cdot \frac{3 \cdot 10^{-21} [J]}{4 \cdot 10^{-14} [s]}$$

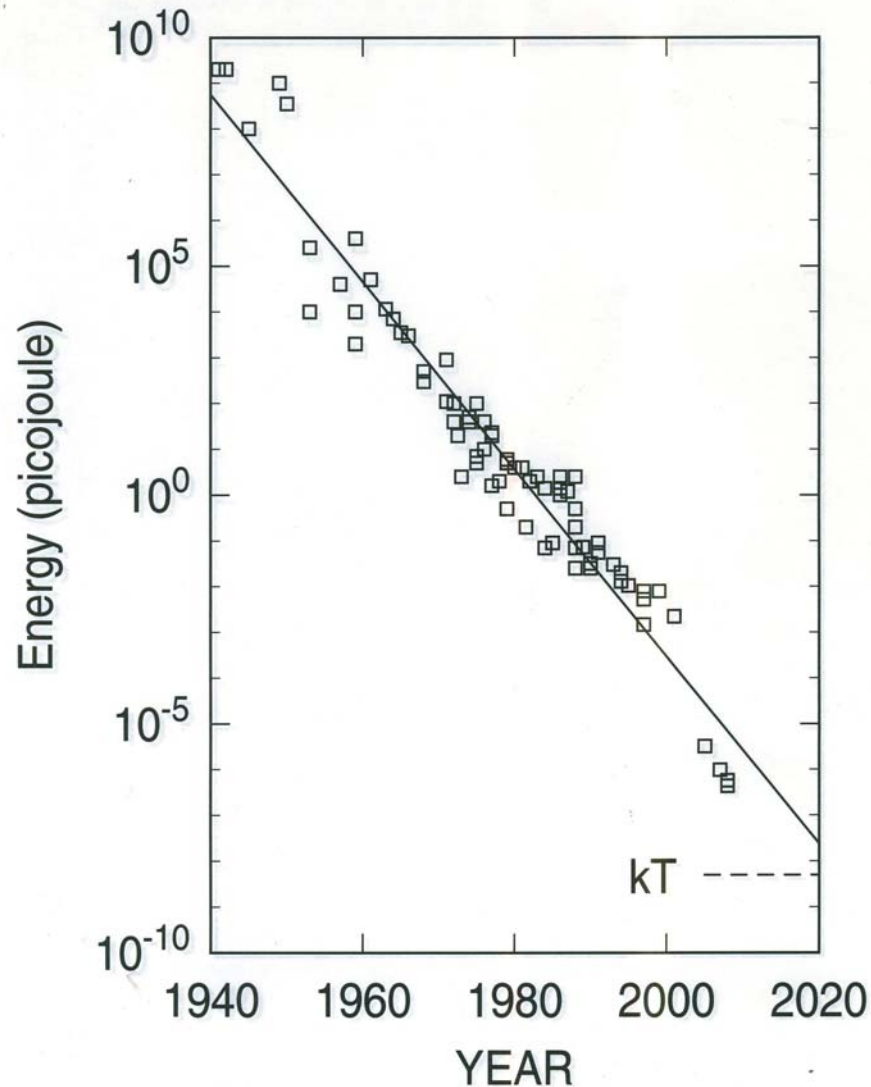
$$E_{bit} = k_B T \ln 2 \approx 3 \cdot 10^{-21} J$$

$$P_{chip} = 4.74 \times 10^6 \frac{W}{cm^2} \quad T=300 K$$

The circuit would vaporize when it is turned on!



FETs approach the “kT” limit



Data compiled by
R. Keyes,
IBM Research Emeritus

- **Power / Heat Generation is the main limiting factor for scaling of device speed and switch circuit density**
- Scaling to molecular sizes may not yield performance increases
 - Forced to trade-off between speed and density
- Optimal dimensions for electronic switches should be ~5-50nm
 - Achievable with Si – easily within the scope of ITRS projections
- Going to other materials for FETs will likely achieve only “one-time” percentage gains
- ***Need a new device mechanism or computation architecture to enable a new scaling path***

Beyond CMOS Logic: What to look for?

- To beat the power problem requires:
 - A device with a lower energy, room temperature switching mechanism
 - or
 - A system that operates out of equilibrium or recovers operation energy as part of the logic computation

■ Required characteristics:

- Scalability
- Performance
- Energy efficiency
- Gain
- Operational reliability
- Room temp. operation



Alternative state variables

- Spin–electron, nuclear, photon
- Phase
- Quantum state
- Magnetic flux quanta
- Mechanical deformation
- Dipole orientation
- Molecular state

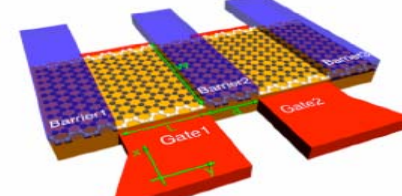
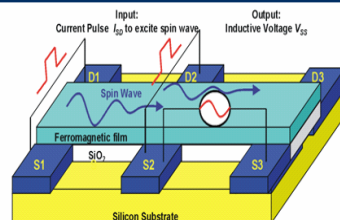
■ Preferred approach:

- CMOS process compatibility
- CMOS architectural compatibility

- **NRI Mission: Demonstrate novel computing devices capable of replacing the CMOS FET as a logic switch in the 2020 timeframe.**
 - These devices should **show significant advantage over ultimate FETs** in power, performance, density, and/or cost to enable the semiconductor industry to **extend the historical cost and performance trends** for information technology.
 - To meet these goals, NRI pursues five research vectors:
 - Device with alternative state vector
 - Non-equilibrium systems
 - Non-charge data transfer (interconnects)
 - Nanoscale phonon engineering for thermal management
 - Directed self-assembly of these new devices
 - Finally, it is desirable that these technologies be **capable of integrating with CMOS**, to allow exploitation of their potentially complementary functionality in heterogeneous systems and to enable a smooth transition to a new scaling path.

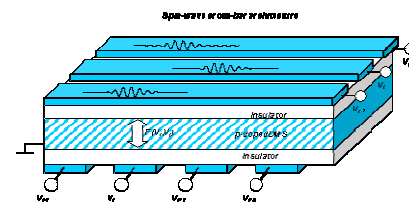
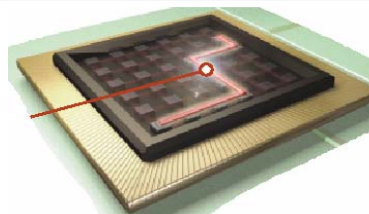
NEW DEVICE

Device with alternative state vector



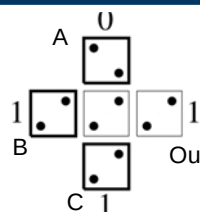
NEW WAYS TO CONNECT DEVICES

Non-charge data transfer



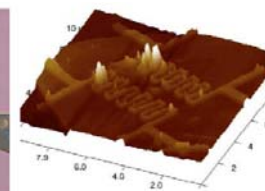
NEW METHODS FOR COMPUTATION

Non-equilibrium systems



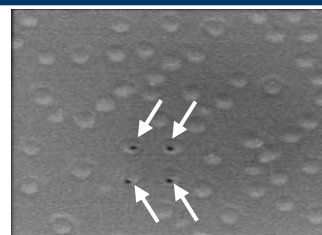
NEW METHODS TO MANAGE HEAT

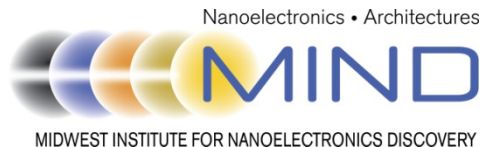
Nanoscale phonon engineering



NEW METHODS OF FABRICATION

Directed self-assembly devices





★ Notre Dame
Illinois-UC
Michigan

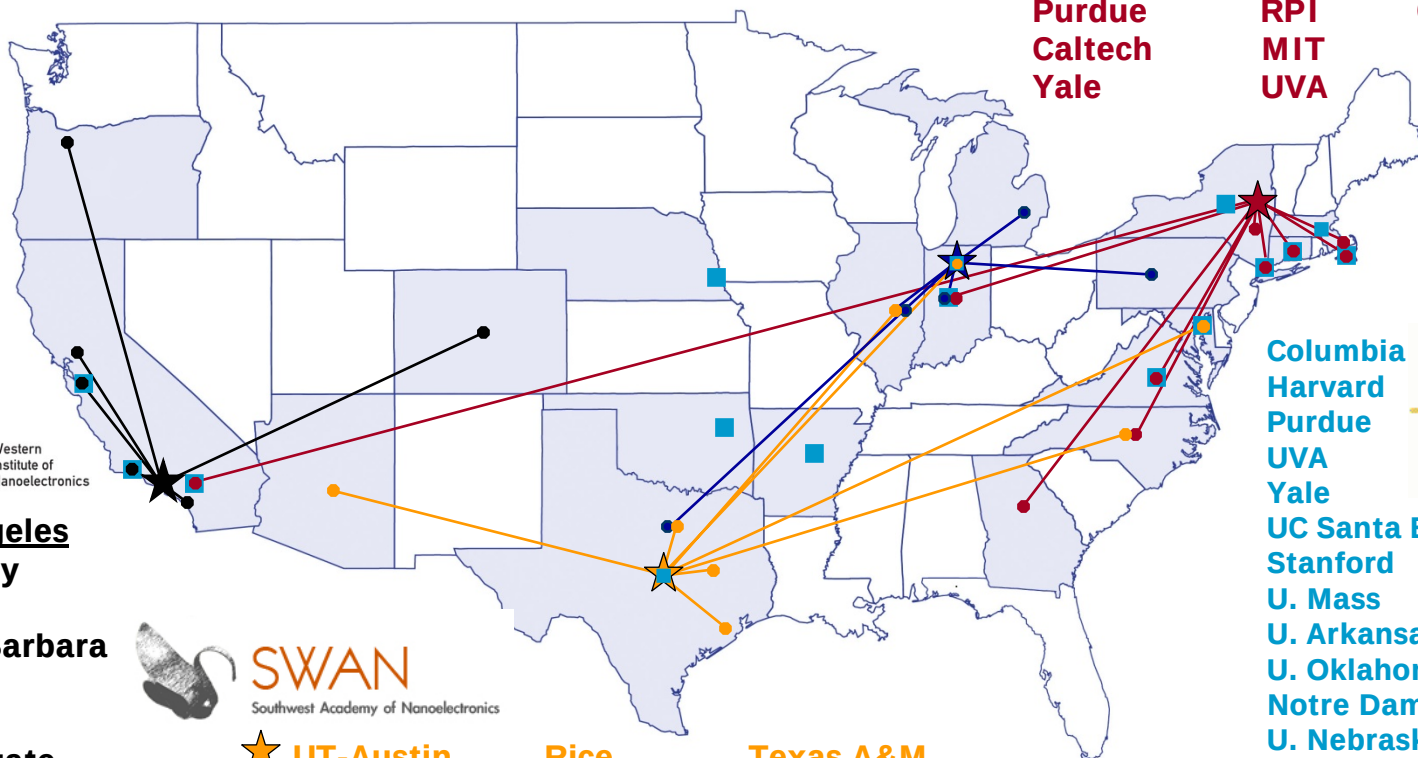
Purdue
Penn State
UT-Dallas



★ SUNY-Albany
Purdue
Caltech
Yale

GIT
RPI
MIT
UVA

Harvard
Columbia
NCSU



Western
Institute of
Nanoelectronics

★ UC Los Angeles
UC Berkeley
UC Irvine
UC Santa Barbara
Stanford
U Denver
Portland State



SWAN

Southwest Academy of Nanoelectronics

★ UT-Austin
UT-Dallas
U. Maryland

Rice
ASU
NCSU

Texas A&M
Notre Dame
Illinois UC

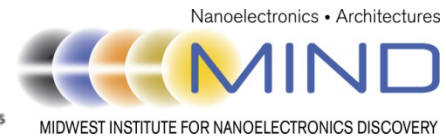
Columbia
Harvard
Purdue
UVA
Yale
UC Santa Barbara
Stanford
U. Mass
U. Arkansas
U. Oklahoma
Notre Dame
U. Nebraska/Lincoln
U. Maryland
Cornell
UT Austin
Caltech



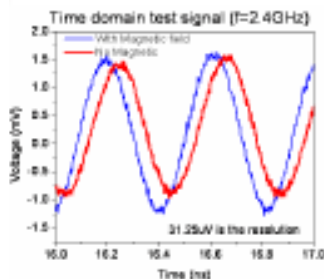
Over 30 Universities in 19 States



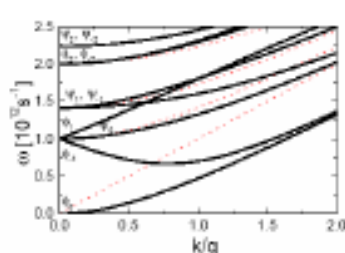
- Leveraging industry, university, and both state & fed government funds, and driving university nanoelectronics infrastructure



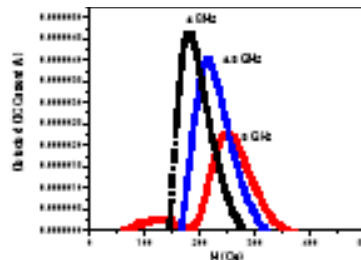
WIN Western Institute of Nanoelectronics	INDEX Institute for Nanoelectronics Discovery & Exploration	SWAN SouthWest Academy for Nanoelectronics	MIND Midwest Institute for Nanoelectronics Discovery
UCLA , UCSB, UC-Irvine, Berkeley, Stanford, U Denver, Portland State	SUNY-Albany , GIT, RPI, Harvard, MIT, Purdue, Yale, Columbia, Caltech, NCSU, UVA	UT-Austin , UT-Dallas, TX A&M, Rice, ASU, Notre Dame, Maryland, NCSU, Illinois-UC	Notre Dame , Purdue, Illinois-UC, Penn State, Michigan, UT-Dallas
Theme 1: Spin devices Theme 2: Spin circuits Theme 3: Benchmarks & metrics Theme 4: Spin Metrology	Task I: Novel state-variable devices Task II: Fabrication & Self-assembly Task III: Modeling & Arch Task IV: Theory & Sim Task V: Roadmap Task VI: Metrology	Task 1: Logic devices with new state-variables Task 2: Materials & structs Task 3: Nanoscale thermal management Task 4: Interconnect & Arch Task 5: Nanoscale characterization	Theme 1: Energy Efficient Devices Theme 2: Energy Efficient Architectures



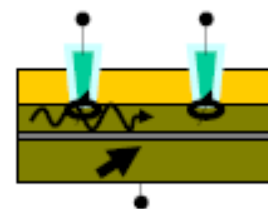
Modulation of spin wave by magnetic field



Simulation of spin wave generation by electric field (UC Berkeley)



Demonstration of Spin Rectification via spin valve (UCLA)

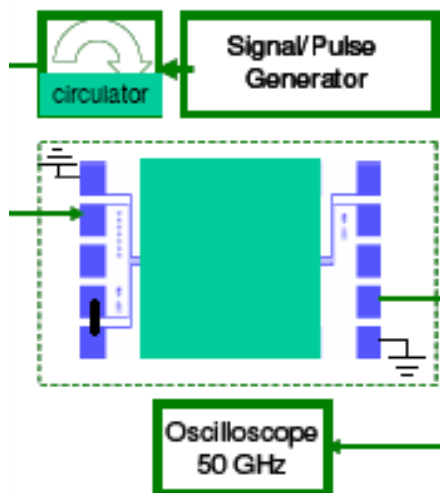


Spin Wave amplification (Stafor)

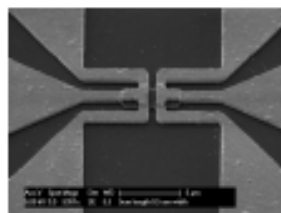
2006

2007

2008/09



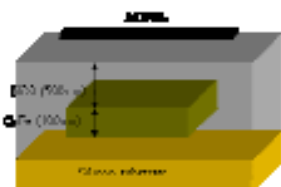
Established spin wave characterization



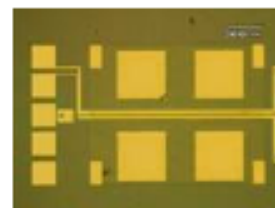
Spin Waveguides (UCSB)



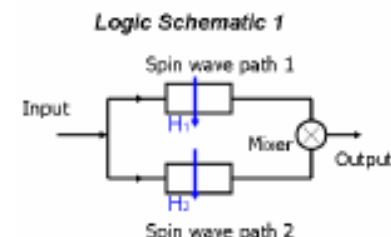
Fabricated structures using PZT and BFO



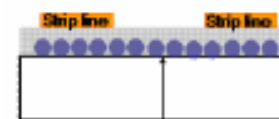
Design spin wave devices and gates



Structures to reduce Eddy Currents



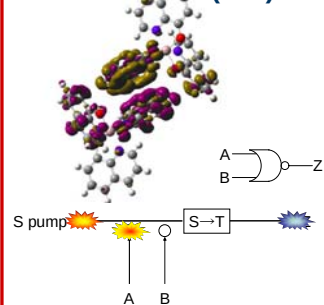
Spin wave circuits (UCSB/UCLA)



Optimize spin wave device

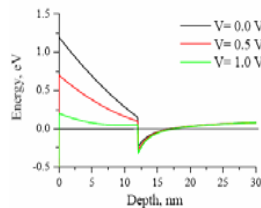
Molecular Excitons Spintronics

Baldo et al (MIT)



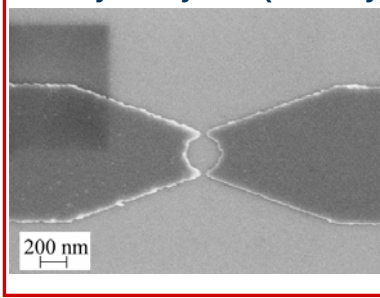
Quantum Dot Modeling

Shur et al (RPI)



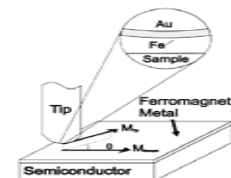
Quantum Dot Devices

Oktyabrsky et al (UAlbany)



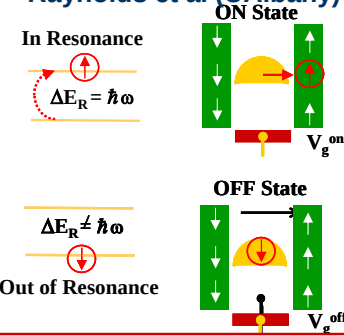
Ballistic Spin Devices

Labella et al (UAlbany)



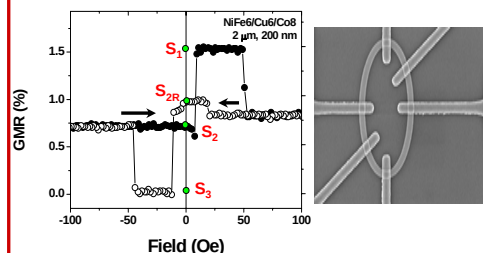
Single Electron Spin Devices

Raynolds et al (UAlbany)



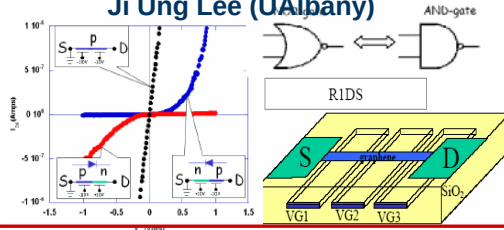
Magnetoelectronic Devices

Multi bits logic Ross et al (MIT)



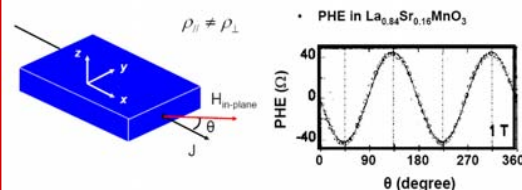
Reconfigurable One-Dimensional (1D) Switch (R1DS)

Ji Ung Lee (UAlbany)



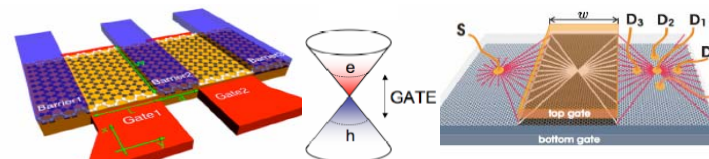
Logical Switches based on Complex Oxides

Ahn et al (Yale)



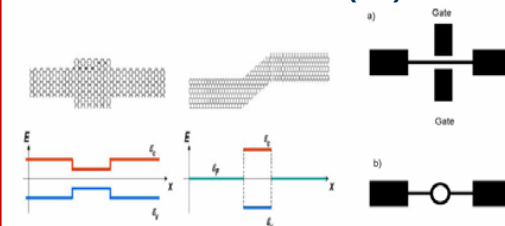
Graphene based Quantum Devices

Charles Marcus (Harvard)



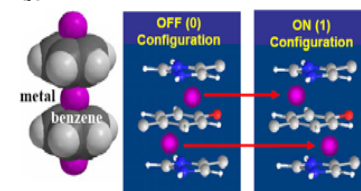
Graphene Nanowire Switches

Murali and DeHeer (GT)



Molecular Nanowire Switches

Kaloyeros et al (UAlbany)

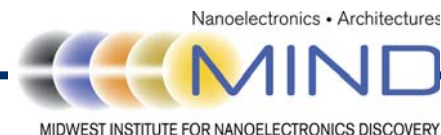
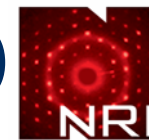


Post CMOS Switches



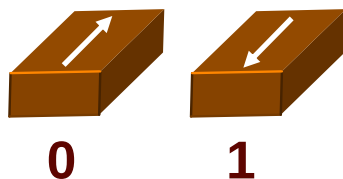
Magnetic Quantum Cellular Automata (MQCA)

M. Niemier, Notre Dame



Schematic

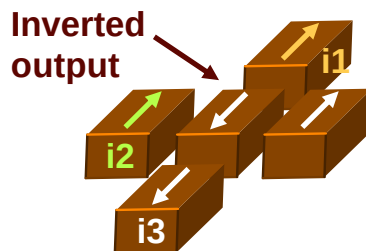
Device



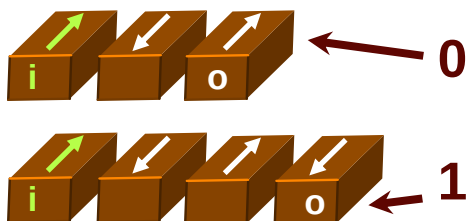
Wire



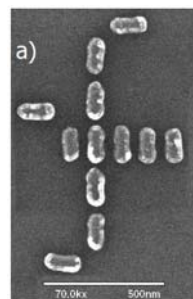
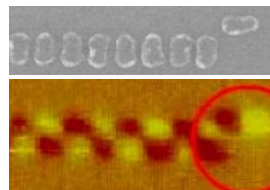
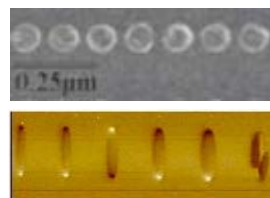
Gate



Inverter

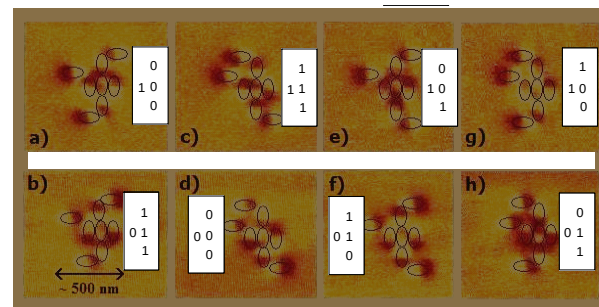


Experimental



R. Cowburn, M. Welland, "Room temperature magnetic quantum cellular automata," *Science* **287**, 1466, 2000
A. Imre, "Experimental Study of Nanomagnets for Magnetic QCA Logic Applications," U. of Notre Dame, Ph.D. Dissertation.

A. Imre, et. al., "Majority logic gate for Magnetic Quantum-Dot Cellular Automata," *Science*, vol. 311, No. 5758, pp. 205–208, January13, 2006.



A. Imre, et. al. "Magnetic Logic Devices Based on Field-Coupled Nanomagnets," *NanoGiga* 2007.

A. Imre, et. al., "Majority logic gate for Magnetic Quantum-Dot Cellular Automata," *Science*, vol. 311, No. 5758, pp. 205–208, January13, 2006.

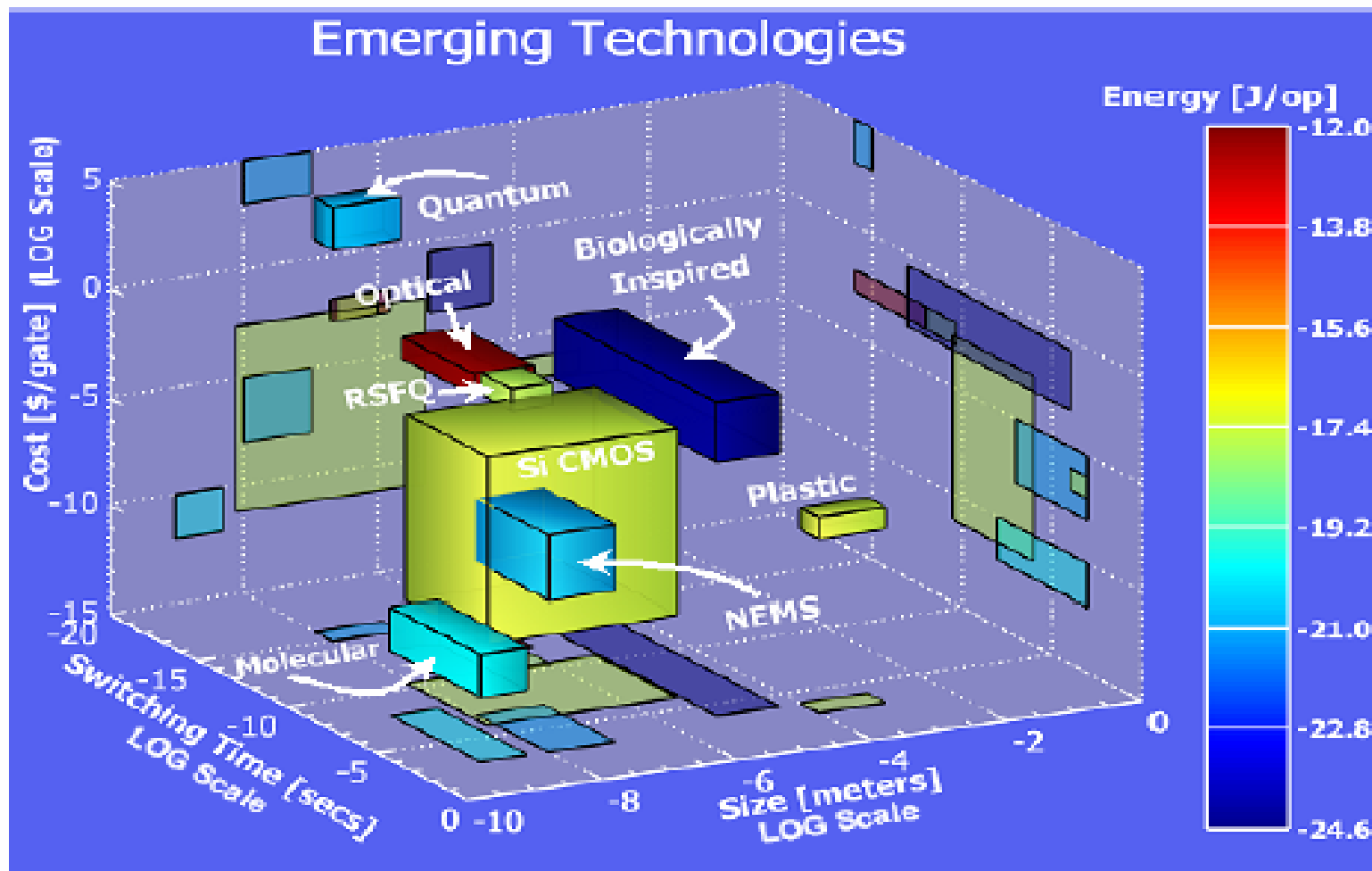
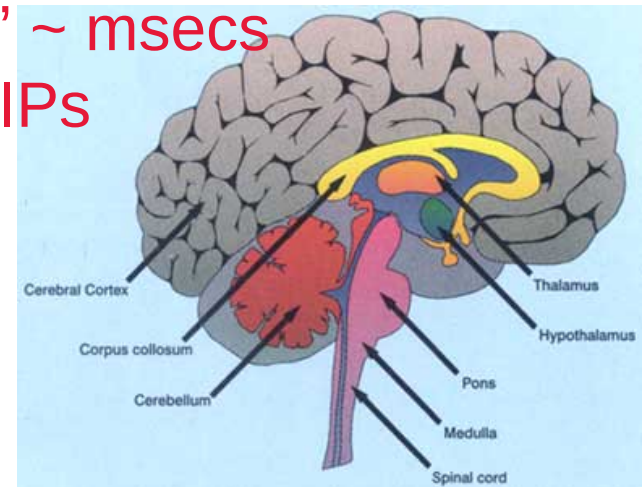


Figure 52 Parameterization of Emerging Technologies and CMOS—Speed, Size, Cost, and Switching Energy

- Many different device ideas being considered – some ‘likely’ attributes compared to CMOS:

- Slower
- Denser / 3D
- Local interconnect focused
- Uniform arrays / sea-of-gates
- Variability still an issue

‘Switch’ ~ msecs
~ 10^8 MIPs
~30W



Proof of concept?

- Architecture / System Question:
 - How to get high computation throughput with these attributes?

- Power will continue as the principal scaling issue for all IC applications
 - CMOS will continue to scale over at least the next decade, with emphasis on utilizing increasing transistor density over increasing frequency

- Any new technology must overcome the power / performance limits of a charge-based FET to continue the scaling trend of increased function / dollar
 - Does the device offer the prospect of lower energy storage / operation than CMOS?
 - Does the computation system offer the prospect of non-equilibrium or energy-recovery in operation?

Nanoelectronics Research Initiative

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